ABSTRACT

A thermosetting and active energy ray curable resin composition is disclosed which contains, as active constituents, a polymer having a (meth)acryl equivalent of 100 to 300 g/eq, a hydroxyl value of 50 to 550 mgKOH/g, an epoxy equivalent of 7000 g/eq or more and a weight-average molecular weight of 5000 to 100000 and a heat-curing agent. A transfer material is also disclosed which includes a protective layer formed of the heat-crosslinking reaction product of the resin composition on a base sheet. A method of producing a molded article includes, after adhering the transfer material to a molded article or after applying the transfer material to the inside of a mold, filling a cavity of the mold with a resin by injection to form a molded article and simultaneously adhere the transfer material on the surface of the molded article, removing the base sheet and irradiating the surface of the molded article with an active energy ray to form the protective layer. Thus, a thermosetting and active energy ray curable resin composition can be provided which is used for protective layers of transfer materials, and imparts excellent wear and abrasion resistance and chemical resistance to the protective layers and prevents occurrence of cracks at curved faces of molded articles at transfer, as well as a transfer material and a method of producing a molded article.